

Thermal Model
of
Pixel Blade Conceptual Design

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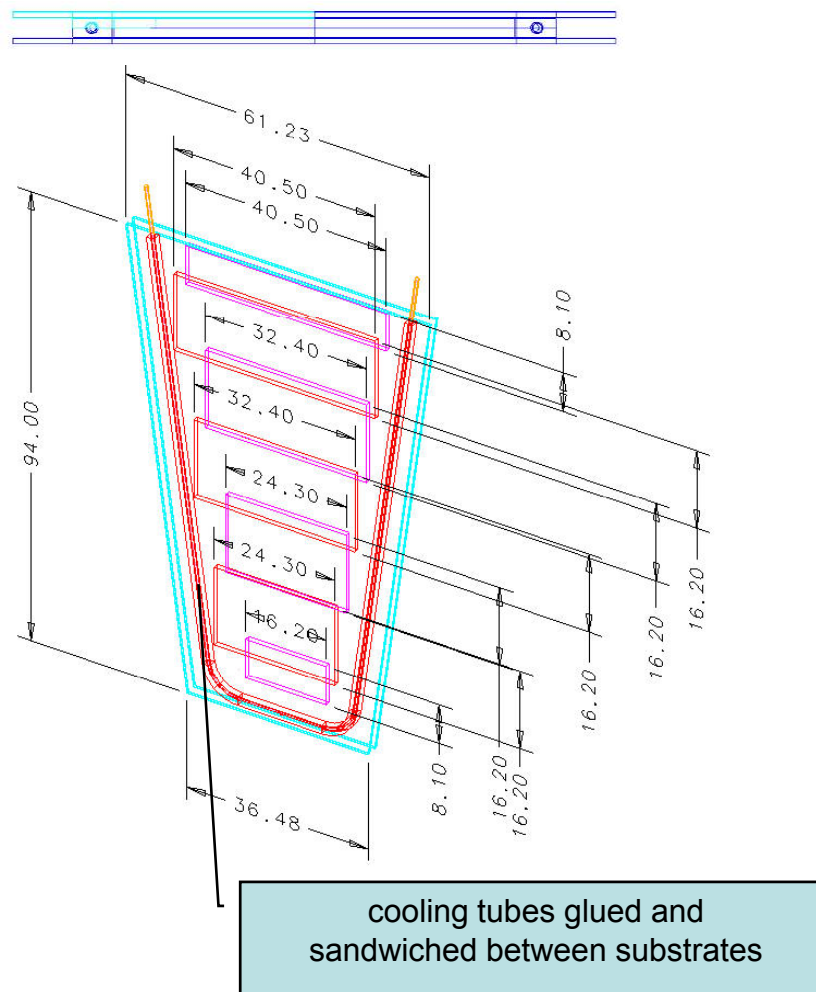
Material Candidates for Substrate

	Density g/cc	Modulus, E_ab Gpa	Modulus, E_c Gpa	Strength Mpa	Thermal K_ab W/m-K	Thermal K_c W/m-K	cte_ab ppm/K	cte_c ppm/K	Rad L, XU cm
Porous Materials									
fuzzy C, 5% pr	0.11	-	-		-	55	-	1.0	406.7
carbon foam, low density	0.25	0.9			15	20	3.5		170.8
SiC foam, 8% packing ratio	0.26	2.8	2.8		11	11	2.2	2.2	166.1
RVC foam (vitreous C)	0.30	0.1	0.1	0.3	0.5	0.5	2.2	2.2	142.3
carbon foam, medium density	0.35	3.0		-1.6	20	25	3.5		122.0
carbon foam, high density	0.45	5.0		-3.5	25	40	3.5		94.9
poco-foam, 25% pr	0.55	20.7	20.7	-2.07	45	135	2.5	2.5	77.6
rohacell	0.03	0.0	0.0	1	0.0	0.0	37.0	37.0	1497.7
Solid Non-metallic Materials									
pyrolytic graphite, PGS	1				600	15.0	0.9	32.0	42.7
peek	1.32	3.6	3.6	92.9	0.2	0.2	46.8	46.8	35.0
CoolPoly E5101 (PPS)	1.70	13.0	13.0	45.0	20	20	15.0	15.0	26.5
CFRP (M46J-epoxy)	1.61	18.1	7.3		56	0.7	0.0	30.2	26.5
glassy C	1.65	20.0	20.0		5	5	3.0	3.0	25.9
CFRP (K13C2U-epoxy)	1.75	483.0	6.2		320	0.5	-1.0	26.0	24.4
CFRP (K139-EX1515)	1.76	154.0	6.4		63	0.4	-0.8	30.4	24.3
Poco graphite ACF-10Q	1.77	11.0	11.0	69.0	60	60	7.6	7.6	24.1
C-C composite (carbon fiber/carbon matrix)	1.80	152.0	4.8		225	150	2.0	2.0	23.7
SiC	3.21	466.0	466.0	-3900	40	40	3.3	3.3	8.1
G10 (glass fiber/epoxy)	1.8	17.2		262.0	0.3	0.3	11.9	11.9	19.4
pyrolytic graphite, TPG	2.26	18.7*	0.0		1700*	10	-1.0	25.0	18.9
Alumina Silicate	2.80			17.5	1.2	1.2	2.9	2.9	14.2
Vespel SP1 Polyimide	1.43	2.4	2.4	87.3	0.3	0.3	54.0	54.0	31.9
CVD Diamond	3.51	1000.0	1000.0	400.0	2000	2000	1.0	1.0	12.0
DLC (diamond-like carbon) coating									
Solid Metallic									
Be	1.85	290.0	290.0	276	145	145	11.6	11.6	35.4
AlBeMet	2.10	200.0	200.0	192	210	210	13.9	13.9	16.1
BeO	2.90	345.0	345.0	138000	330	330	7.6	7.6	13.3
Aluminum Nitride (AlN)	3.26	331.0	331.0	-2100	165	165	4.5	4.5	10.3
silicon	2.33	110.3	110.3	-120	120	120	2.6	2.6	9.4
aluminum 6061-T6	2.76	69.0	69.0	379	237	237	23.4	23.4	8.9
stainless steel 304	7.86	200.0	200.0	517	16	16	15.1	15.1	1.8
copper 101	8.94	129.7	129.7	350	391	391	17.6	17.6	1.4



Basic Design of the Pixel Blade

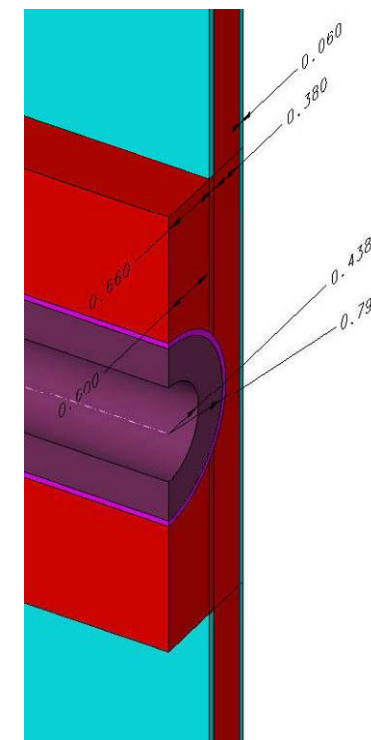
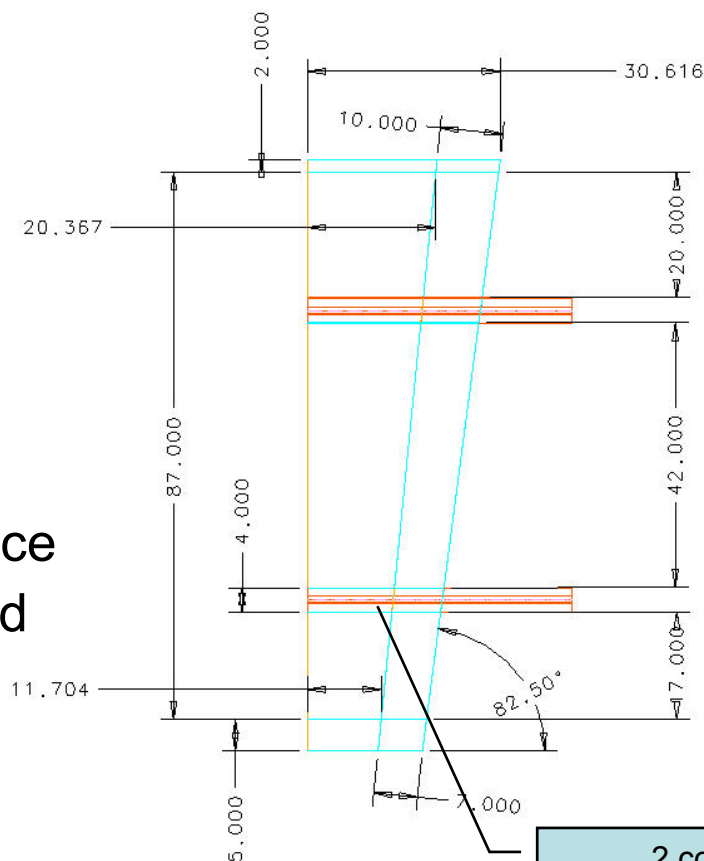
- The tentative basic design of the pixel blade -- 2 substrates with cooling tubing sandwiched in between.
- TPG is tentatively selected for the substrate and it is encapsulated with one ply of CFRP.
- CO₂ cooling is selected, and the heat transfer area of the small cooling tube is enlarged by embedding it directly within the TPG substrate.
- The major task is to design the cooling layout and how to bond the cooling tubing to the TPG substrate properly.





Quarter FEA Blade Model (Half Substrate)

- Two tubing running laterally
- Substrate thickness:
 - 0.06 mm 1-ply CFRP
 - 0.38 mm TPG
 - 0.06 mm 1-ply CFRP
- Area spreader and substrate are in one piece
- Regular epoxy was used for the adhesive



2 cooling tubes glued and sandwiched with TPG area spreaders



Some FEA were done

- All 150% heat load, 3.75 W on half substrate;
- All -30C heat sink temperature on tubing inner surface;
- 3 cases reported:
 - 0.88 mm ID ss tubing with 0.66 mm thick TPG spreader (0.6 mm from cf surface)
 - 0.88 mm ID ss tubing with 0.46 mm thick TPG spreader (0.4 mm from cf surface)
 - 0.88 mm ID al tubing with 0.66 mm thick TPG spreader (0.6 mm from cf surface)

Sensor Dimensions

	width, mm	height, mm	area, mm ²
1	40.5	8.1	328.05
2	40.5	16.2	656.1
3	32.4	16.2	524.88
4	32.4	16.2	524.88
5	24.3	16.2	393.66
6	24.3	16.2	393.66
7	16.2	8.1	131.22

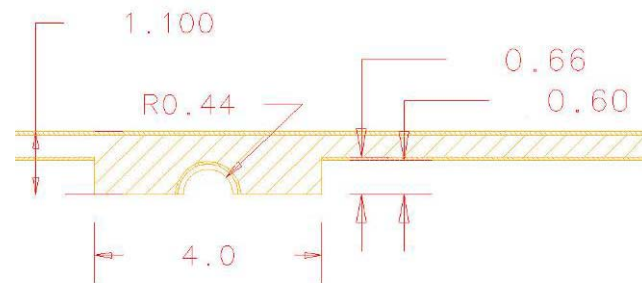
total area = 2952.45 or 29.5245 cm²

2X3 End Disks Heat Load, W

ROC	962
control & driver	27
sensors	365
Total	1354

Each end disk has 24 blades, or 48 substrates,
 heat load per substrate = $1354/6/48 = 4.701$

Heat load density = $4.7W/29.5245 = 0.159 \text{ W/cm}^2$



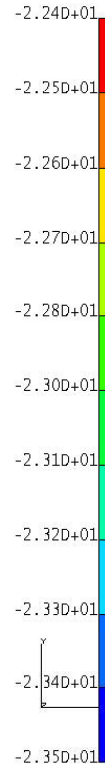
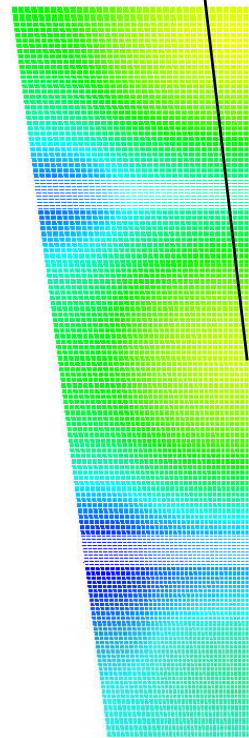
0.06 cf + 0.38 TPG + 0.06 cf Substrate

0.66 spreader + ss tubing

150% heat load, 3.75W

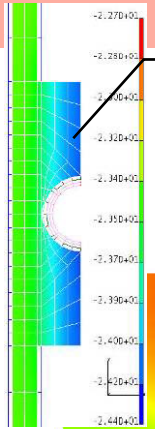


-22.4C

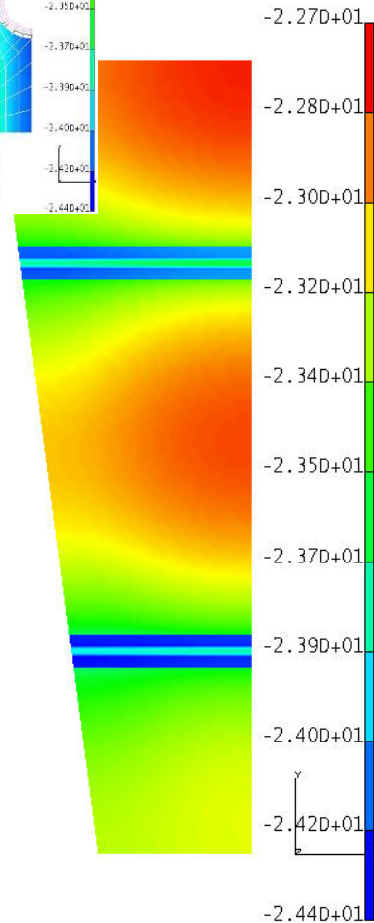


$\Delta T = 1.1$ C across top facing

Substrate FEA



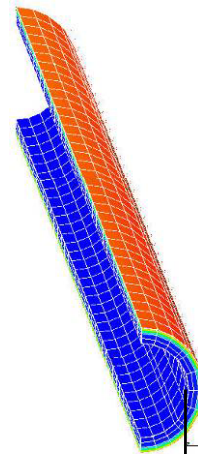
0.66 mm thick TPG Spreader



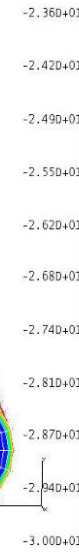
$\Delta T = 1.7$ across TPG

CMS Pixel Mech Upgrade Workshop

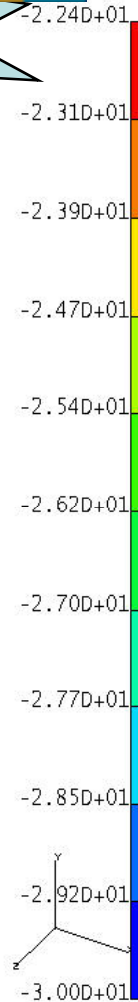
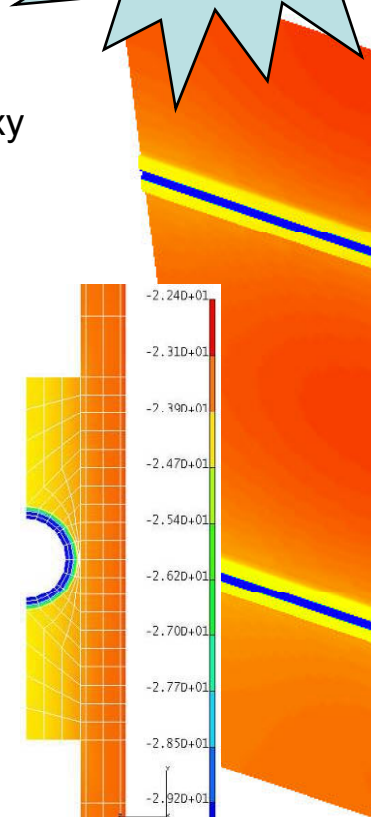
$\Delta T = 6.4$ C across tubing & epoxy



.0035" t ss tubing



Total % RL for whole blade = 0.59%



$\Delta T = 7.6$ C across the whole model

0.06 cf + 0.38 TPG + 0.06 cf Substrate
 0.46 spreader + ss tubing

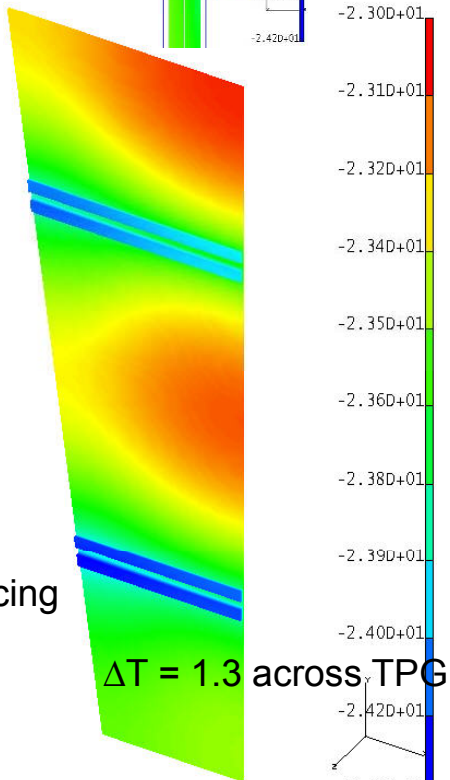
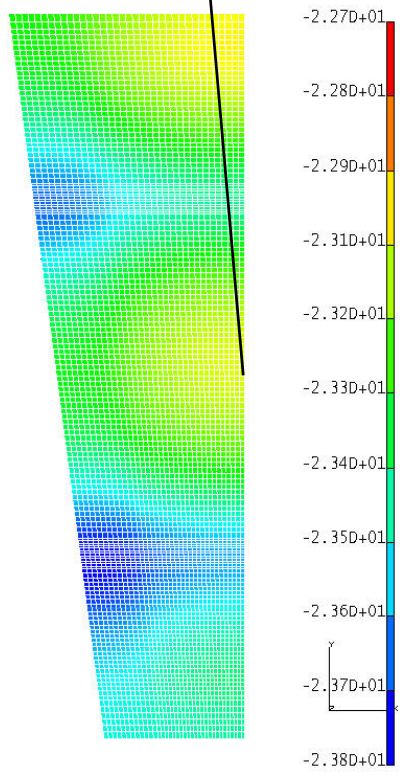
150% heat load, 3.75W



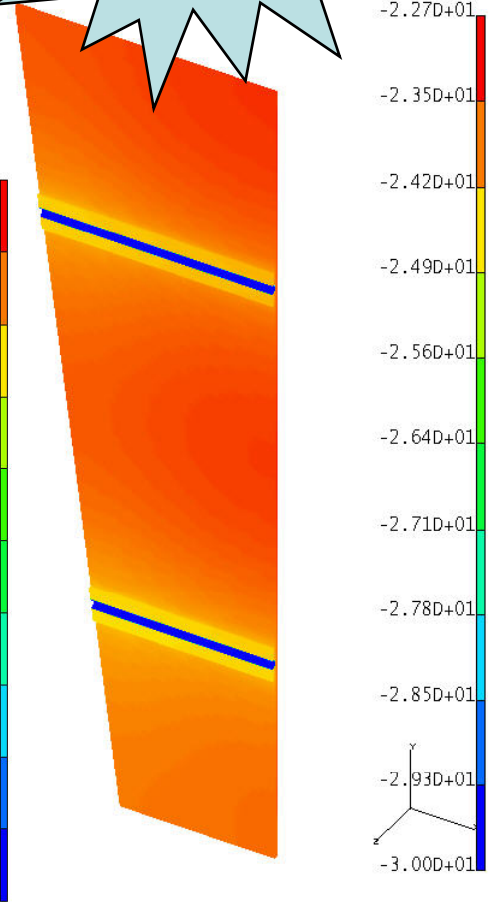
-22.7C

0.46 mm thick
 TPG Spreader

Total % RL
 for whole blade
 = 0.57%



$\Delta T = 6.4\text{ C}$
 across tubing & epoxy



$\Delta T = 1.1\text{ C}$ across top facing

$\Delta T = 1.3$ across TPG

ss tubing

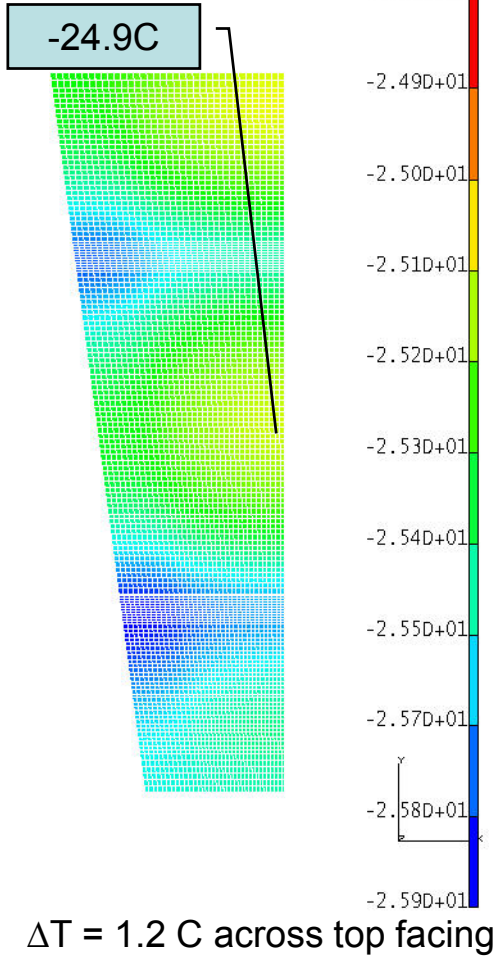
$\Delta T = 7.3\text{ C}$
 across the whole model

Substrate FEA

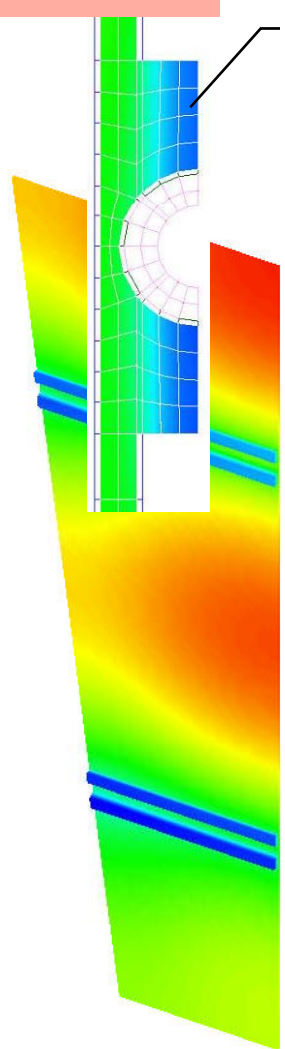
CMS Pixel Mech Upgrade
 Workshop

0.06 cf + 0.38 TPG + 0.06 cf Substrate
 0.66 spreader + al tubing

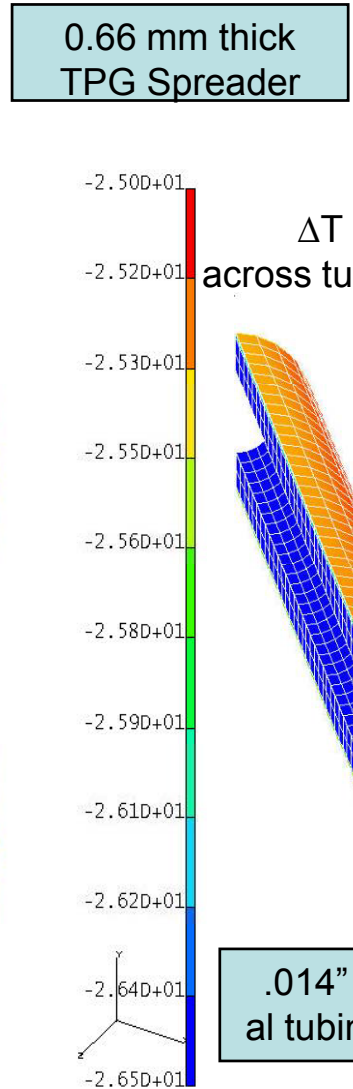
150% heat load, 3.75W



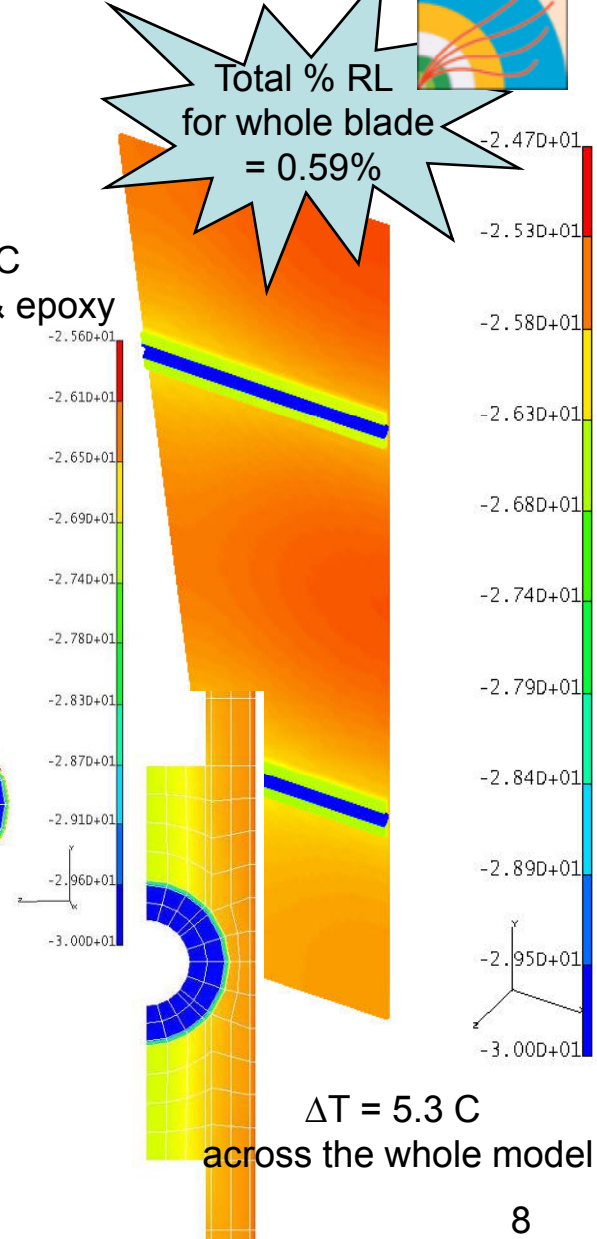
Substrate FEA



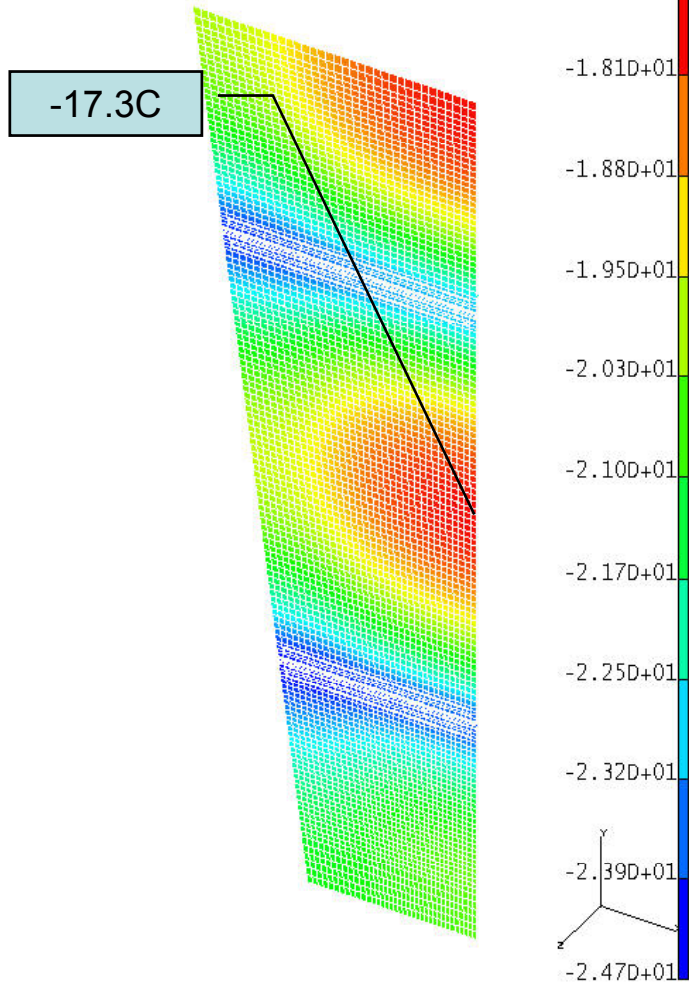
$\Delta T = 1.5$ across TPG



CMS Pixel Mech Upgrade Workshop



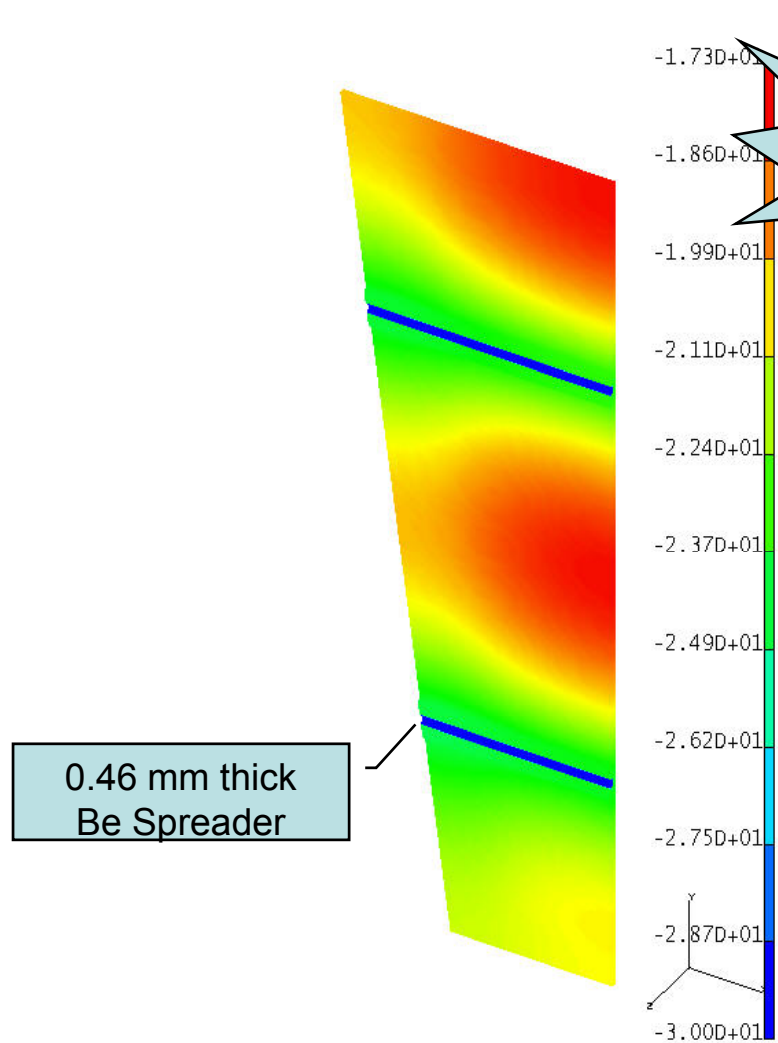
0.50 Beryllium Substrate
0.46 spreader + ss tubing



$\Delta T = 7.4 \text{ C}$ (6.1 C more)
across Be substrate

Substrate FEA

150% heat load, 3.75W



$\Delta T = 12.7 \text{ C}$ (5.4 C more)
across the whole model

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Workshop

Two Tubing were considered in this FEA



	OD, inches	t, inches	OD in mm	ID in mm	t, mm	Pressure, bar with SF = 3	per half tube X2 mass, g	X0, g/cm ²	Eff. % Rad L
SS 316L	0.0415	0.0035	1.0541	0.8763	0.0889	112	0.103	14.1	0.02%
Al 3003 H14	0.0625	0.014	1.5875	0.8763	0.3556	299	0.185	24.6	0.02%

Both tubing have the same ID and basically the same effective % rad L over the substrate area.

% RL Details and Summary

<< Masses are evenly distributed over the substrate area 4592 mm² >>



Configuration	B-T1, 2 horizontal tubing with TPG area spreader thickness in mm =					0.66				
Whole substrate	material	t or l, mm	area, mm ²	volume, mm ³	density, g/cc	mass, g	X0, g/cm ²	Eff. % Rad L	Heat	
TPG	TPG	0.380	4592.488	1745.146	2.260	3.944	42.7	0.20%	150%	
CF	CF	0.120	4592.488	551.099	1.760	0.970	42.8	0.05%		
Area Spreader	TPG	97.469	2.400	233.926	2.260	0.529	42.7	0.03%		
epoxy	for substrate									
tube, half	ss 316L	97.469	0.135	13.137	7.860	0.103	14.1	0.02%		
epoxy, half	for tubing		97.469	0.083	8.069	1.200	42.6	0.00%		
Coolant, half	CO2 liq.	97.469	0.302	29.392	1.030	0.030	36.2	0.002%		
Total % RL for half blade								0.30%	ΔT	
Total % RL for whole blade								0.59%	7.6	
Configuration	B-T1, 2 horizontal tubing with TPG area spreader thickness in mm =					0.46				
Whole substrate	material	t or l, mm	area, mm ²	volume, mm ³	density, g/cc	mass, g	X0, g/cm ²	Eff. % Rad L	Heat	
TPG	TPG	0.380	4592.488	1745.146	2.260	3.944	42.7	0.20%	150%	
CF	CF	0.120	4592.488	551.099	1.760	0.970	42.8	0.05%		
Area Spreader	TPG	97.469	1.600	155.951	2.260	0.352	42.7	0.02%		
epoxy	for substrate									
tube, half	ss 316L	97.469	0.135	13.137	7.860	0.103	14.1	0.02%		
epoxy, half	for tubing		97.469	0.083	8.069	1.200	42.6	0.00%		
Coolant, half	CO2 liq.	97.469	0.302	29.392	1.030	0.030	36.2	0.002%		
Total % RL for half blade								0.29%	ΔT	
Total % RL for whole blade								0.57%	7.3	
Configuration	B-T1, 2 horizontal tubing with TPG area spreader thickness in mm =					0.66				
Whole substrate	material	thickness, mm	area, mm ²	volume, mm ³	density, g/cc	mass, g	X0, g/cm ²	Eff. % Rad L	Heat	
TPG	TPG	0.380	4592.488	1745.146	2.260	3.944	42.7	0.20%	150%	
CF	CF	0.120	4592.488	551.099	1.760	0.970	42.8	0.05%		
Area Spreader	TPG	97.469	2.400	233.926	2.260	0.529	42.7	0.03%		
epoxy	for substrate									
tube, half	al 3003	97.469	0.688	67.069	2.760	0.185	24.6	0.02%		
epoxy, half	for tubing		97.469	0.125	12.153	1.200	42.6	0.00%		
Coolant, half	CO2 liq.	97.469	0.302	29.392	1.030	0.030	36.2	0.002%		
Total % RL for half blade								0.30%	ΔT	
Total % RL for whole blade								0.59%	5.3	
Configuration	B-T1, 2 horizontal tubing with TPG area spreader thickness in mm =					0.46				
Whole substrate	material	thickness, mm	area, mm ²	volume, mm ³	density, g/cc	mass, g	X0, g/cm ²	Eff. % Rad L	Heat	
Be	Be	0.380	4592.488	1745.146	1.850	3.229	65.2	0.11%	150%	
Be	Be	0.120	4592.488	551.099	1.850	1.020	65.2	0.03%		
Area Spreader	Be	97.469	1.600	155.951	1.850	0.289	65.2	0.01%		
epoxy	for substrate									
tube, half	ss 316L	97.469	0.135	13.137	7.860	0.103	14.1	0.02%		
epoxy, half	for tubing		97.469	0.083	8.069	1.200	42.6	0.00%		
Coolant, half	CO2 liq.	97.469	0.302	29.392	1.030	0.030	36.2	0.002%		
Total % RL for half blade								0.17%	ΔT	
Total % RL for whole blade								0.34%	12.7	

Note: The total % RL for the existing whole blade design = 0.29% + 0.86% + 0.31% (2 Be substrates + al channel + coolant) = 1.46%

Comparisons between TPG and Beryllium

Results Comparison

	Eff. % Rad L	ΔT overall	ΔT substrate	cte
TPG/CF	0.57%	7.3	1.3	-1
Be	0.34%	12.7	7.4	11.6
Difference	-0.23%	5.4	6.1	10.6
% toTPG	-41%	74%	469%	-1060%

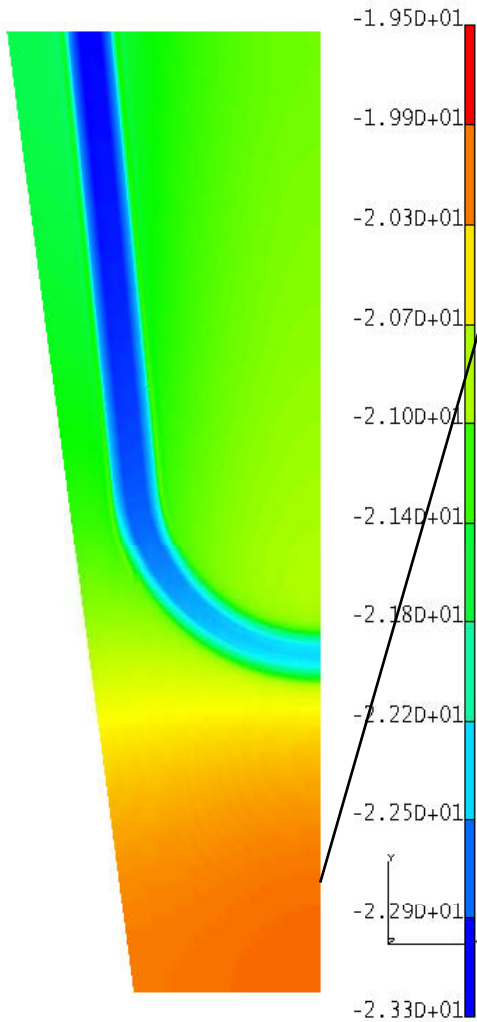
**** It should be noted that this cooling arrangement, with cooling tube directly under the modules, is favorable to beryllium as it has much better thermal conductivity in out of plane direction.**

Properties Comparison

	Thermal K _{ab} W/m-K	Thermal K _c W/m-K	Rad L, X0 cm	K _{ab} *Rad L W/K	K _c *Rad L W/K
CFRP - 1ply	126	0.6	24.3	30.6	0.1
TPG @ -20C	1960	10	18.9	370.4	1.9
Be	145	145	35.4	51.3	51.3

Conf. A-T1: 0.06 cf + 0.50TPG + 0.06 cf Substrate

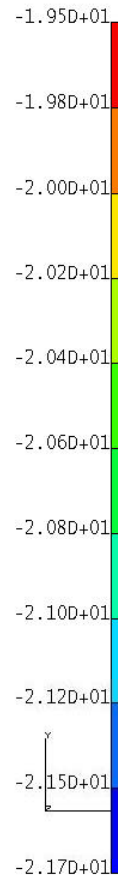
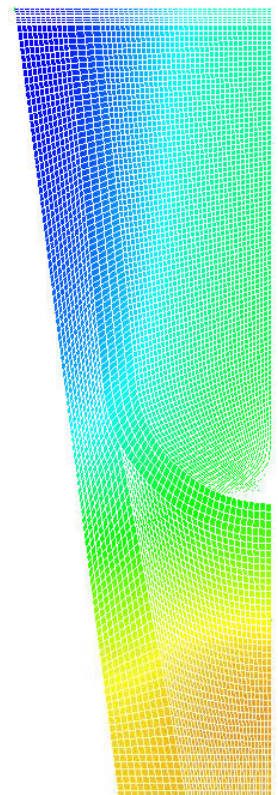
200% heat load (0.318 W/cm²)
4.44 W on this half substrate



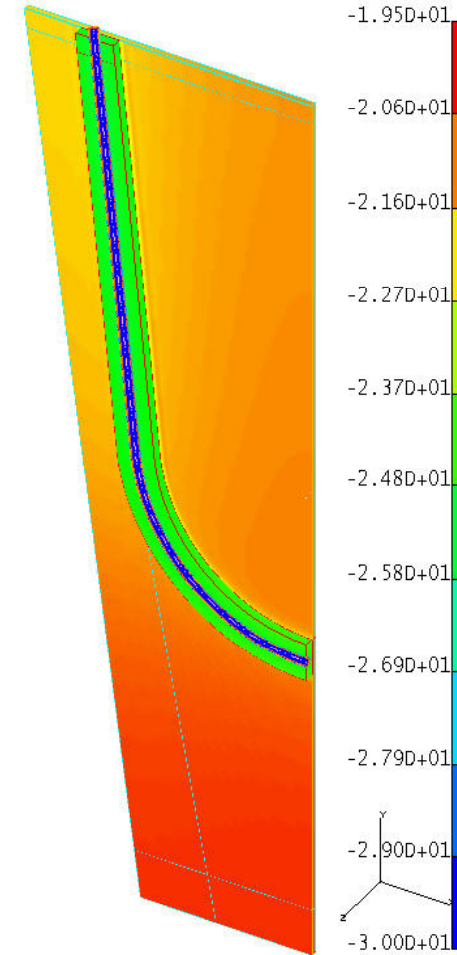
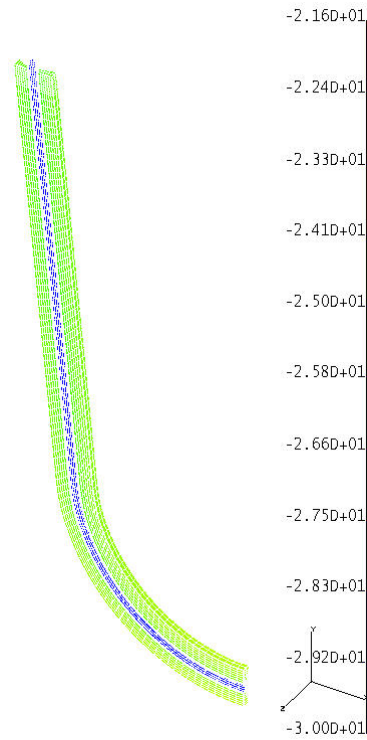
$\Delta T = 3.8$ C across substrate
 $\Delta T = 2.2$ C across cf top facing

Substrate FEA

-19.5C



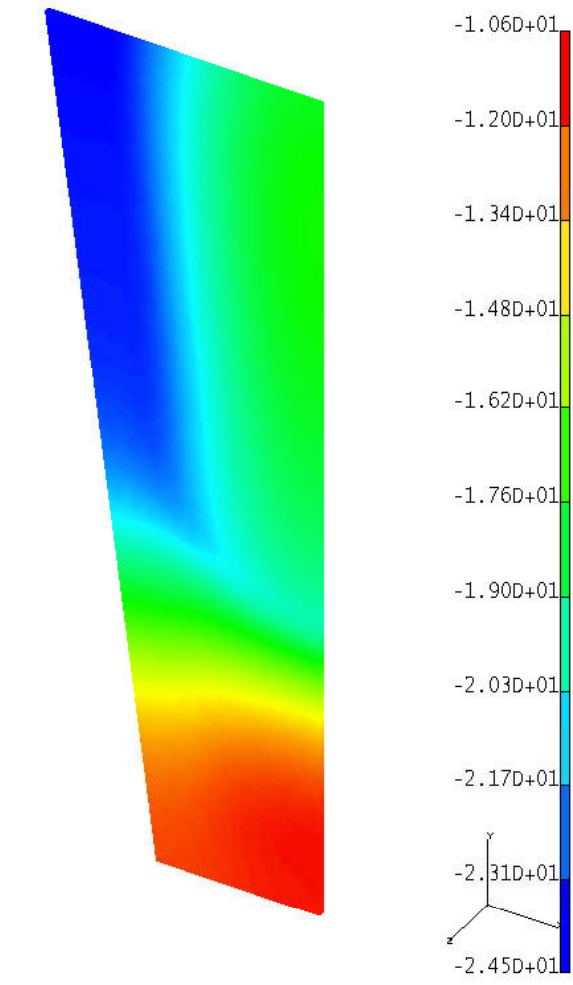
$\Delta T = 8.4$ C
from tube to epoxy



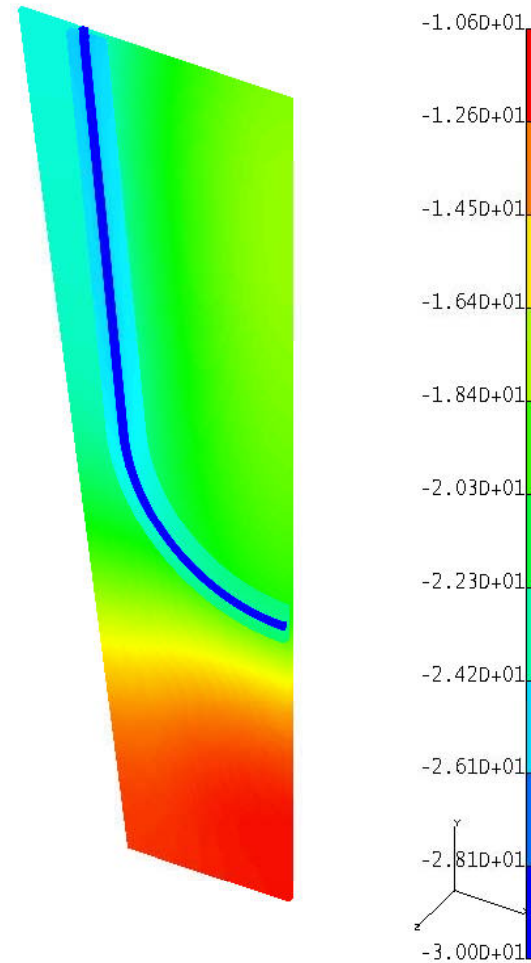
Overall $\Delta T = 10.5$ C

Conf. A: 0.62 mm thick Beryllium Substrate

200% heat load (0.318 W/cm²)
4.44 W on this half substrate



$\Delta T = 13.9 \text{ C}$ (10.1C more)
across substrate



Overall $\Delta T = 19.4 \text{ C}$ (8.9C more)

Preliminary Conclusions



- Although beryllium substrate could offer the least % Rad L, the large temperature distribution over the substrate is thermally inferior than that of TPG.
- Using TPG as substrate in incorporating with small-size CO2 tubing appeared positive and offered an overall material saving and outstanding thermal performance at a reasonable cost. (120mm x 100mm x 1.04mm ~\$200 per piece)
- Further FEA checks on thermal stresses and displacements with module glued on substrate is needed and will be followed.

Back Up Slides



Items Selected for the Conceptual Design

- Material selected for Substrate
 - TPG laminated with carbon-fiber reinforced plastic
 - Low mass ($X_0 = 18.9$ cm)
 - Radiation hard
 - Dimensionally stable
 - Very high thermal conductivity
~ 1700 W/mK at room temperature
- Cooling selected for Substrate
 - High-pressure CO₂ with small tubing
 - Low mass
 - Radiation hard
 - High thermal performance

>> small cooling tube will be used.

The major task is thus to design the cooling layout and how to bond the cooling tubing to the TPG substrate properly.

K Values used in this FEA



Thermal Conductivities K of TPG, In-Plane

Temp in K	K in W/m-K
70	2920
80	3432
90	3784
100	3984
150	3624
200	2600
250	1960
273.2	1784
300	1600
350	1352
400	1168
500	904
600	744

Thermal K of TPG, Out-of-Plane = 10 W/mK

- 0° Carbon-Fiber Facing, In-Plane = 126 W/mK
- 0° Carbon-Fiber Facing, Out-of-Plane = 0.6 W/mK
- epoxy (3M DP190 Gray) = 0.38 W/mK



Thermal Pyrolytic Graphite (TPG)

- A unique form of pyrolytic graphite
- Made by the decomposition of a hydrocarbon gas within vacuum furnace
- Exceptionally high thermal conductivity (in-plane $k =$ up to 1700 W/m-K, out-of-plane $k =$ 10W/m-K at room temperature)
- Low CTE (in-plane = -1 ppm/C, out-of-plane = 25 ppm/C)
- Low density = 2.26 g/cc
- Long $X0 =$ 18.9 cm ($X0*k =$ 321 W/K vs. 51 W/K of Be)
- Only available in rigid but brittle sheet, non-bendable.
- Friable, needs encapsulation; carbon fiber composite is chosen for needed rigidity within material budget constraint.

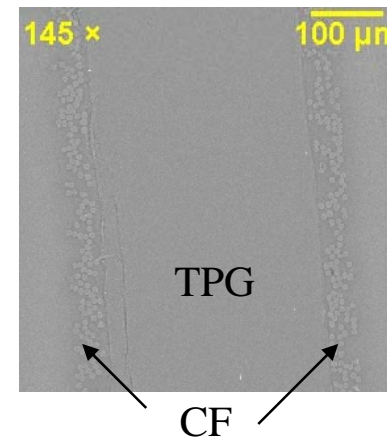
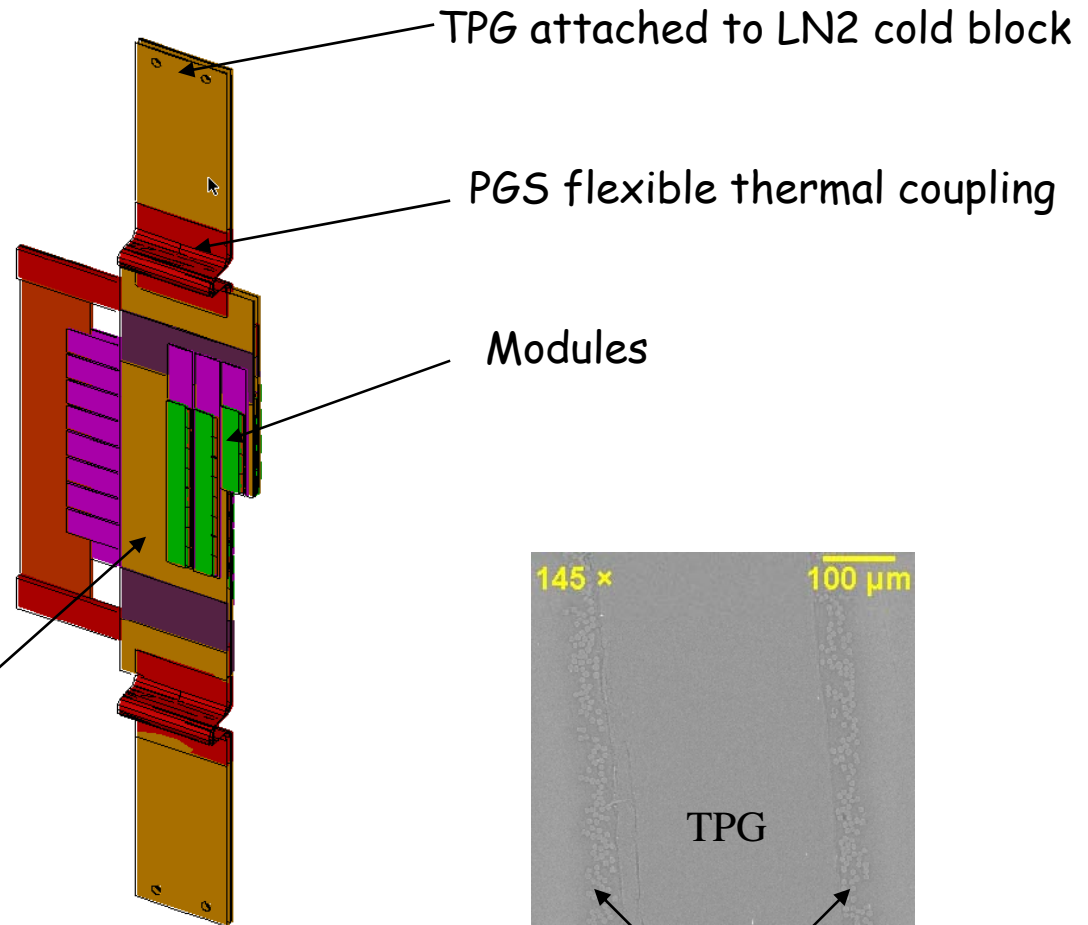
- Vendors:
 - Momentive Performance Materials (<http://advceramics.com/>)
 - MiNTEQ (<http://pyrographite.com/>)



TPG Experience at FermiLab

TPG was firstly proposed to use for BTeV pixel detector in 2003.

TPG encapsulated with one ply of CFRP for the facing

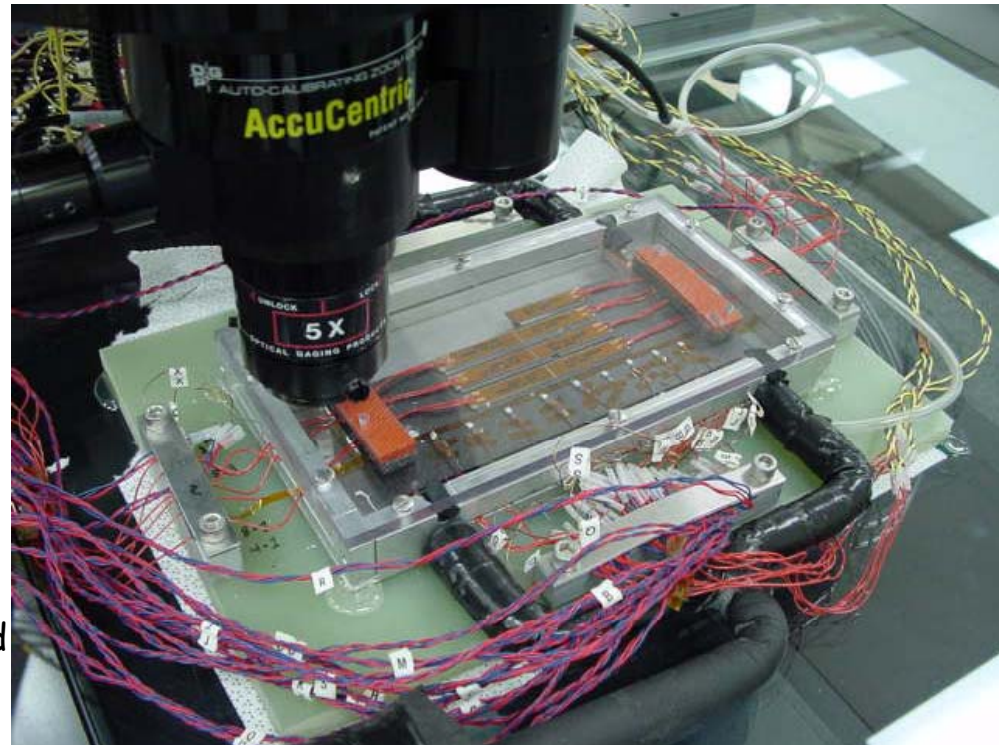




TPG Experience at FermiLab ...continued (1)

The BTeV prototype was made and thermal cyclic tests with heaters and cooling on and off were conducted. Results were satisfactory, no alarming problem was found.

- Test was conducted within a dry box with small amount of nitrogen flowing
- Kapton heaters on dummy silicon were used to simulate module heat load
- Cooling contacts were provided at ends
- An optical camera was used to observe the target displacements
- RTDs were glued on substrate to record thermal data
- Pin & hole engagement at large end
- Pin & slot engagement at small end

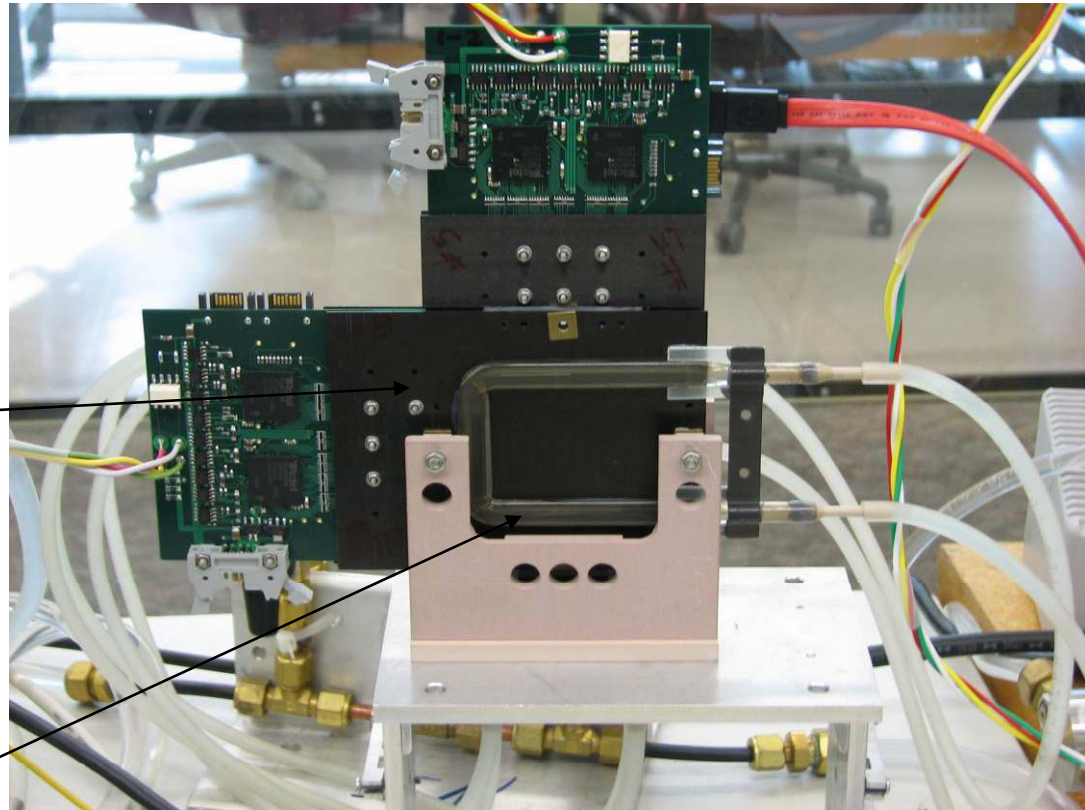




TPG Experience at FermiLab - continued (2)

It was successfully used for MTest Pixel Detector this year.

TPG encapsulated with two plies of CFRP for the facing



PEEK Cooling tube glued on the back of TPG

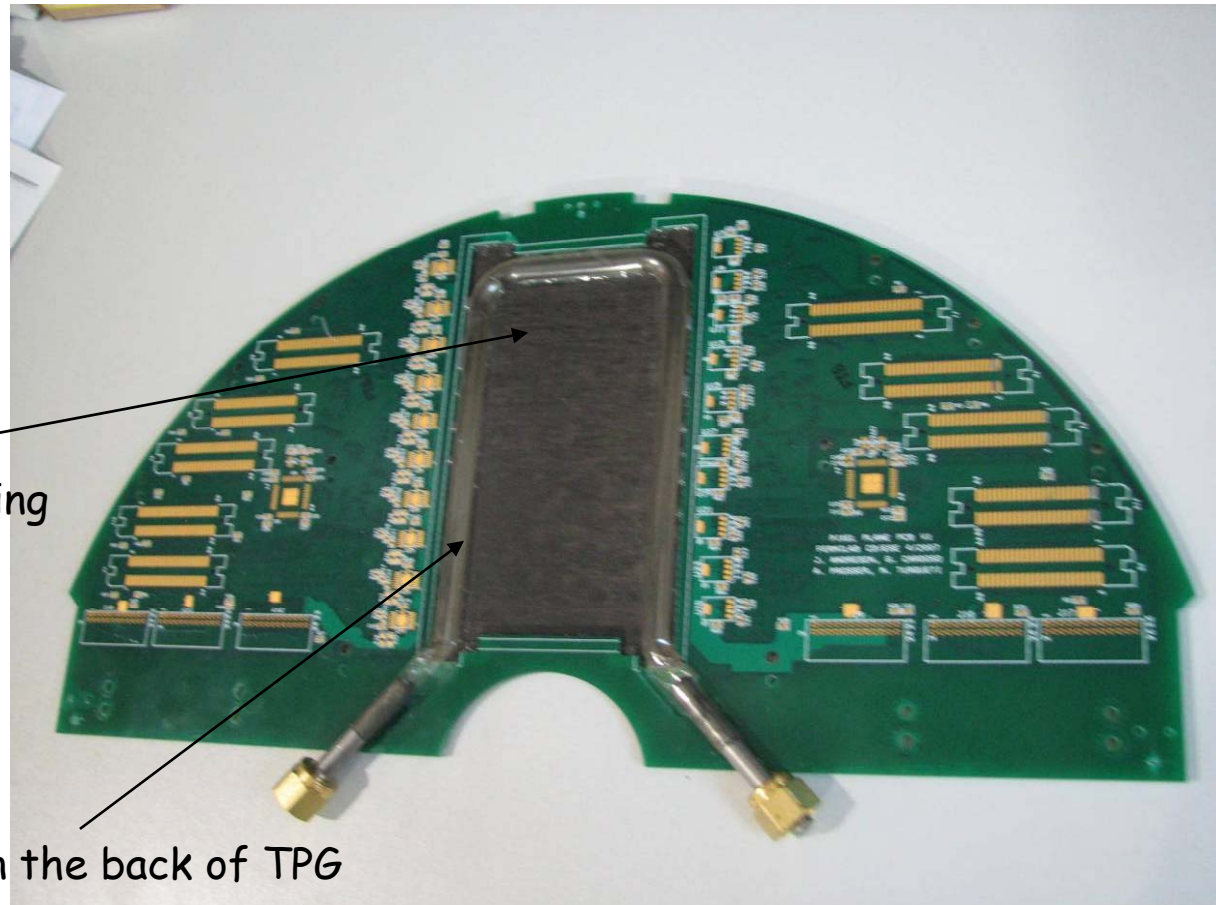


TPG Experience at FermiLab - continued (3)

It is planned to use for the PHENIX pixel detector as well.

TPG encapsulated with two plies of CFRP for the facing

PEEK Cooling tube glued on the back of TPG

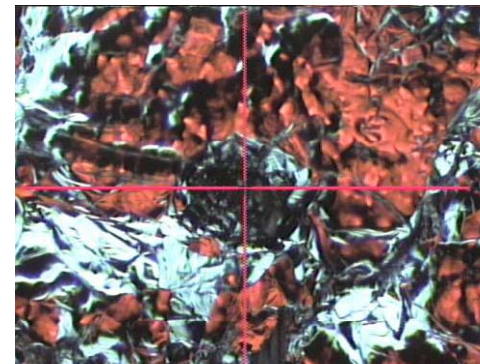
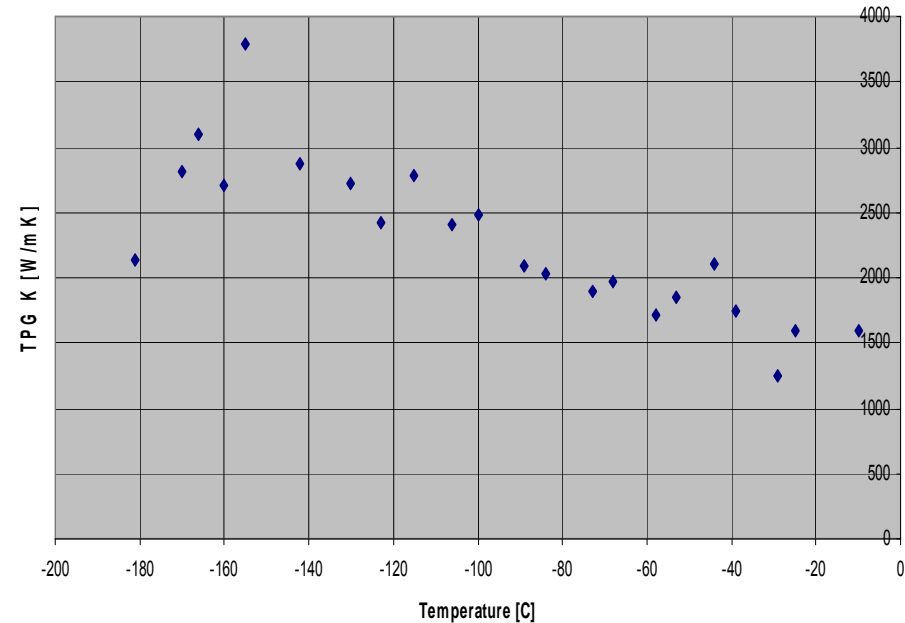




TPG Experience at FermiLab - continued (4)

TPG Thermal Conductivity [W/m K]

- No alarming problems were found.
- Perforated holes drilling on TPG was needed before encapsulation. It would improve the rigidity of the substrate.
- Tensile pulling test on encapsulated TPG samples were done, and the improved strength was verified.
- Thermal conductivity measurement of TPG were checked and its high thermal K characteristic at low temperatures was verified.
- Plasma cleaning on the CFRP encapsulated TPG was checked, the thermal performance could be slightly improved as a thin layer of the impregnated epoxy was removed.
- TPG might not be very flat due to the relief of internal stress when made at the factory. It could be flattened somewhat when CFRP was added.



This perforated hole was basically filled up completely with epoxy



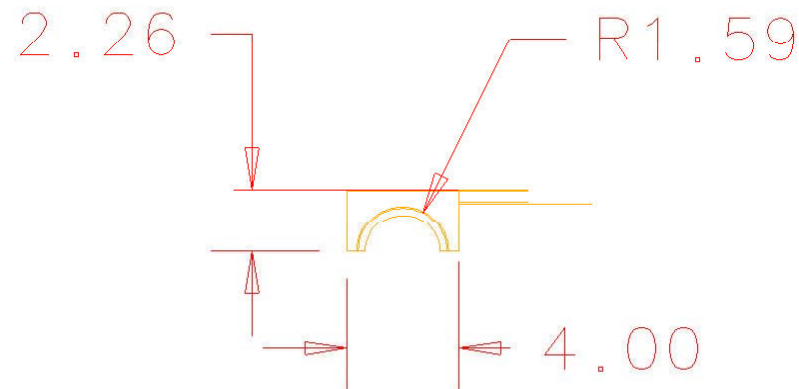
Distance between substrate to substrate within the blade

This distance should be as small as possible so that minimum material is effectively used to provide an hermitage coverage of tracking.

Existing design = 4.52 mm

Using this distance as the limiting guideline, it is possible to increase tubing size without thickening the TPG substrate.

Largest possible OD = 1/8" (3.175 mm).





% Rad L of Tubing and corresponding TPG Area Spreader per Substrate

Tubing ss 316L		Pressure, bar with SF = 2	Half Tubing		Rad L due to t	Per Substrate	TPG		Per Substrate	Total/Subs	Total/Blade
OD, inches	t, inches		area, mm^2	mass, g		Rad L over A	Sp area, mm^2	mass, g	Rad L over A	Rad L over A	Rad L over A
0.125	0.01	160	1.165	0.893	1.41%	0.14%	3.049	0.672	0.03%	0.17%	0.34%
0.119	0.007	118	0.795	0.609	0.99%	0.09%	3.118	0.687	0.04%	0.13%	0.26%
0.108	0.009	167	0.903	0.692	1.27%	0.11%	3.195	0.704	0.04%	0.14%	0.28%
0.094	0.009	191	0.775	0.594	1.27%	0.09%	3.204	0.706	0.04%	0.13%	0.25%
0.094	0.005	106	0.451	0.345	0.71%	0.05%	3.204	0.706	0.04%	0.09%	0.18%
0.082	0.008	195	0.600	0.460	1.13%	0.07%	3.133	0.690	0.04%	0.11%	0.21%
0.082	0.0055	134	0.426	0.327	0.78%	0.05%	3.133	0.690	0.04%	0.09%	0.17%
0.0715	0.006	168	0.398	0.305	0.85%	0.05%	3.010	0.663	0.03%	0.08%	0.16%
0.0715	0.004	112	0.274	0.210	0.56%	0.03%	3.010	0.663	0.03%	0.07%	0.13%
0.0645	0.009	279	0.506	0.388	1.27%	0.06%	2.897	0.638	0.03%	0.09%	0.18%
0.0645	0.006	186	0.356	0.273	0.85%	0.04%	2.897	0.638	0.03%	0.07%	0.15%
0.0645	0.004	124	0.245	0.188	0.56%	0.03%	2.897	0.638	0.03%	0.06%	0.12%
0.0615	0.005	163	0.286	0.219	0.71%	0.03%	2.841	0.626	0.03%	0.07%	0.13%
0.0575	0.008	278	0.401	0.307	1.13%	0.05%	2.759	0.608	0.03%	0.08%	0.16%
0.0575	0.005	174	0.266	0.204	0.71%	0.03%	2.759	0.608	0.03%	0.06%	0.12%
0.0575	0.003	104	0.166	0.127	0.42%	0.02%	2.759	0.608	0.03%	0.05%	0.10%
0.0555	0.005	180	0.256	0.196	0.71%	0.03%	2.715	0.598	0.03%	0.06%	0.12%
0.0495	0.0085	343	0.353	0.271	1.20%	0.04%	2.570	0.566	0.03%	0.07%	0.14%
0.0495	0.006	242	0.265	0.203	0.85%	0.03%	2.570	0.566	0.03%	0.06%	0.12%
0.0495	0.004	162	0.184	0.141	0.56%	0.02%	2.570	0.566	0.03%	0.05%	0.10%
0.0455	0.0065	286	0.257	0.197	0.92%	0.03%	2.464	0.543	0.03%	0.06%	0.12%
0.0415	0.0075	361	0.258	0.198	1.06%	0.03%	2.349	0.518	0.03%	0.06%	0.11%
0.0415	0.005	241	0.185	0.142	0.71%	0.02%	2.349	0.518	0.03%	0.05%	0.10%
0.0415	0.0035	169	0.135	0.103	0.49%	0.02%	2.349	0.518	0.03%	0.04%	0.08%
0.0385	0.006	312	0.198	0.151	0.85%	0.02%	2.258	0.497	0.03%	0.05%	0.10%
0.0355	0.006	338	0.179	0.137	0.85%	0.02%	2.162	0.476	0.02%	0.05%	0.09%
0.0355	0.005	282	0.155	0.118	0.71%	0.02%	2.162	0.476	0.02%	0.04%	0.09%
0.0355	0.004	225	0.128	0.098	0.56%	0.02%	2.162	0.476	0.02%	0.04%	0.08%
0.034	0.004	235	0.122	0.093	0.56%	0.01%	2.113	0.465	0.02%	0.04%	0.08%
0.032	0.006	375	0.158	0.121	0.85%	0.02%	2.045	0.450	0.02%	0.04%	0.08%
0.032	0.005	313	0.137	0.105	0.71%	0.02%	2.045	0.450	0.02%	0.04%	0.08%
0.032	0.002	125	0.061	0.047	0.28%	0.01%	2.045	0.450	0.02%	0.03%	0.06%
0.03	0.0035	233	0.094	0.072	0.49%	0.01%	1.975	0.435	0.02%	0.03%	0.07%
0.028	0.006	429	0.134	0.102	0.85%	0.02%	1.903	0.419	0.02%	0.04%	0.07%
0.028	0.004	286	0.097	0.075	0.56%	0.01%	1.903	0.419	0.02%	0.03%	0.07%
0.028	0.0025	179	0.065	0.049	0.35%	0.01%	1.903	0.419	0.02%	0.03%	0.06%